



SCREENING OPTIONS FOR HYBRIDS

STANDARD: "AMPTEK HIGH RELIABILITY SCREENING"

- -Nondestructive Bond Pull (100%), MIL-STD-883, Method 2023
- -Precap Visual: MIL-STD-883, Method 2017, Condition H, low magnification, high magnification
- -Sealing: Welded, Hermetic Seal
- -Marking: Date Code and Serial Number
- -Stabilization Bake: MIL-STD-883, Method 1008, Condition C. +150 °C, 24 hours minimum
- -Temperature Cycle: MIL-STD-883, Method 1010, Condition C. Min. T = -65 °C to +150 °C,
 - 10 minutes each extreme, 5 minutes maximum transfer time, 10 cycles
- -Centrifuge: MIL-STD-883, Method 2001, Condition B. YI axis; 5,000 G's
- -Electrical Test: As per Specifications
- -Burn-In Test: MIL-STD-883, Method 1015, 160 hours at +125 °C
- -Fine Leak Test: MIL-STD-883, Method 1014, Condition A. Rejection if leak rate in excess of 5 x 10⁻⁷ cc/sec.
- -Gross Leak Test: MIL-STD-883, Method 1014, Condition C. Perflourocarbon
- -Electrical Test: As per Specification
- -External Visual: MIL-STD-883, Method 2009

OPTION 1: Includes **STANDARD** Screening plus the following:

- -Particle Impact Noise Detection (PIND), MIL-STD-883, Method 2020
- -Radiographic, MIL-STD-883, Method 2012
- -Final Electrical Tests at +70 °C and -25 °C

OPTION 1+ Screening: Includes **STANDARD** Screening, plus **Option 1** plus the following:

- -SEM on all active components, MIL-STD-883, Method 2018
- -Package evaluation, MIL-STD-883, Sub-Groups 1-4 and 6
- -Substrate Evaluation, MIL-PRF-38534 (Appendix C)
- -Customer Pre-cap Visual Inspection (Optional)
- -Extended Burn-In: MIL-STD-883, Method 1015, Total of 240 hours at +125 °C
- -Lot Qualification: RGA, MIL-STD-883, Method 1018 on 1 to 3 pieces
- -Lot Qualification: 1,000 hours Steady State Life Test at 125 °C on 4 to 10 pieces

OPTION 2: NASA Goddard Space Flight Center Preferred Parts List (PPL-20), GSFC S-311-P698 includes STANDARD Screening, plus OPTION 1 plus the following:

- -Pre-assembly Parts Qualification (Element Evaluation)
- -Package Evaluation
- -Customer Precap Visual Inspection
- -Destructive Bond Pull Test on sample devices
- -Die Shear Test on sample devices
- -Moisture Test
- -Optional extended Burn-In
- -Pre and Post Burn-In Deltas
- -Additional Quality Control Inspections (QCI)
- -Lot Qualification (1,000 hours Steady State Life Test at 125 °C on sample devices)

OPTION 3: Customer supplied Source Control Document

NOTES:

- 1) Option 1 and Option 1+: 100 piece minimum order for each hybrid type.
- 2) Option 2 or Option 3: not always available, please contact Sales Office.
- 3) Price and delivery upon request.